

SOT1073-1

plastic thin fine-pitch ball grid array package; 64 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA64
Package type industry code	TFBGA64
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	14-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	1	-	1.1	1.2	mm
A ₂	package height	0.75	-	0.8	0.85	mm
n ₂	actual quantity of termination	-	-	64	-	



2. Package outline

TFBGA64: plastic thin fine-pitch ball grid array package; 64 balls SOT1073-1

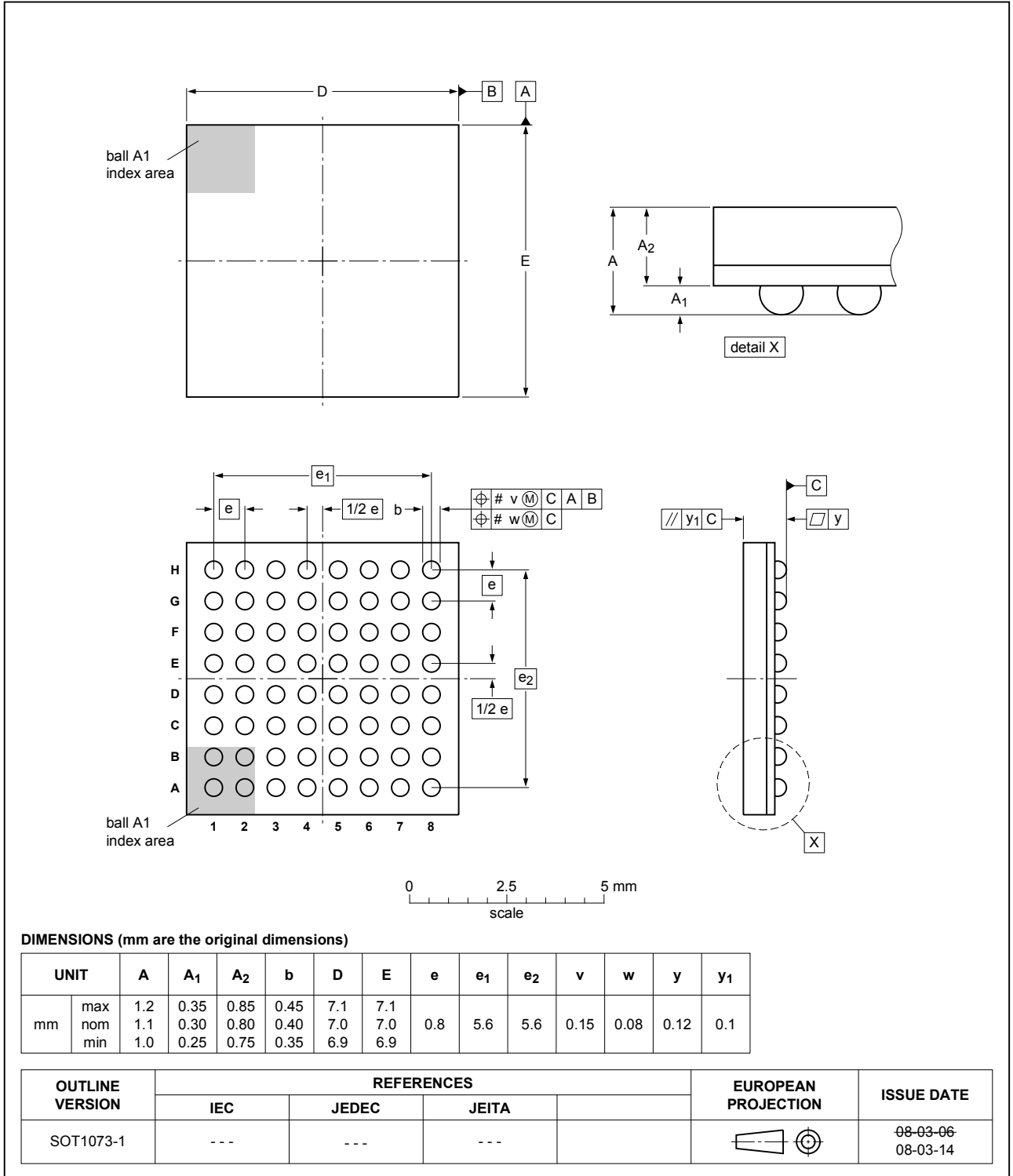
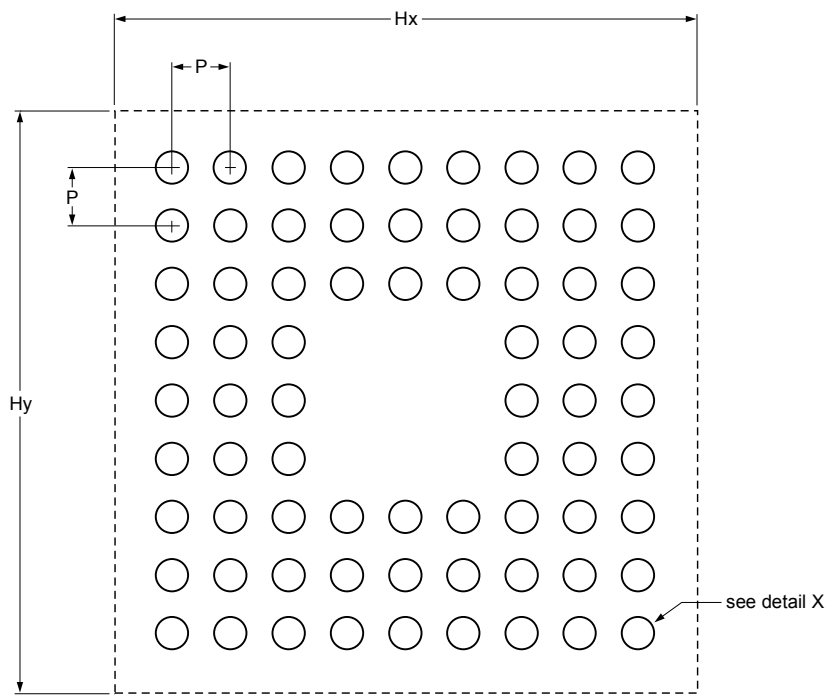


Fig. 1. Package outline TFBGA64 (SOT1073-1)

3. Soldering

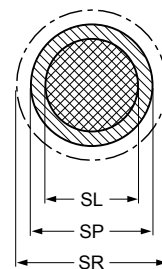
Footprint information for reflow soldering of TFBGA64 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.80	0.330	0.400	0.550	7.400	7.400

sot1073-1_fr

Fig. 2. Reflow soldering footprint for TFBGA64 (SOT1073-1)

4. Legal information

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